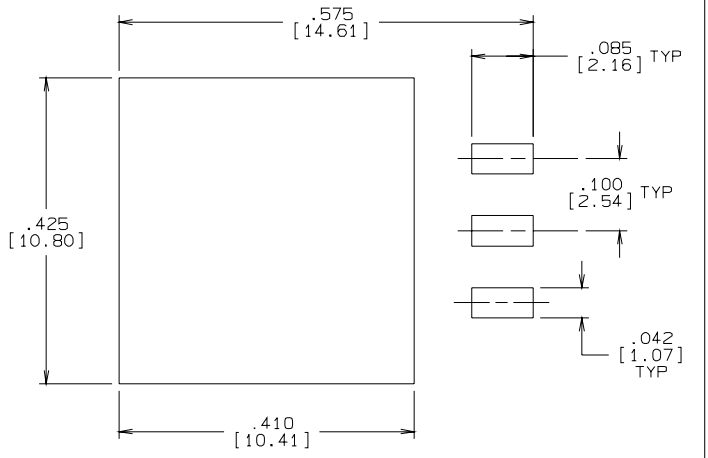


BACK VIEW

CONTROLLING DIMENSION: INCH

REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	09897	07/16/93	MS/FL
B	REV COPLANARITY; DEL STANDOFF DIM, DEL LEADS FROM BACK VIEW.	09955	08/25/93	MS/FL
C	ADD STAND-OFF DIM & NOTE 5.	10153	11/22/93	MS/FL
D	STAND-OFF mm DIM WAS [0.00-0.15]; NOTE 5: ADD mm VALUE.	10179	12/01/93	MS/FL
E	BACK VIEW: .200 [5.08] MIN WAS .250 [6.35] MIN; NOTE 2: 0.08mm WAS 0.05mm.	10777	01/10/95	MS/



LEAD POSITION OVERLAY

- NOTES: UNLESS OTHERWISE SPECIFIED
- STANDARD LEAD FINISH: 200 MICROINCHES / 5.08 MICROMETERS MINIMUM LEAD/TIN 15/85 ON OLIN 194 COPPER OR EQUIVALENT.
 - MAXIMUM VERTICAL BURR ON HEATSINK NOT TO EXCEED .003 INCH / 0.08mm.
 - NO PACKAGE CHIPS, CRACKS OR SURFACE INDENTATION ALLOWED AFTER FORMING.
 - REFERENCE JEDEC BALLOT 10-340 AS OF 06/16/93.
- (5) UNDER ALL CONDITIONS LEAD(S) MUST NOT BE ABOVE THE DATUM PLANE -M- AND NO LEADS MAY BE LOWER THAN .006 INCH / 0.15mm MEASURED FROM DATUM PLANE -M- TO THE BOTTOM OF THE LEADS.

APPROVALS	DATE	National Semiconductor		
DRAWN MARTA SUCHY	07/16/93	2900 Semiconductor dr, Santa Clara, CA 95052-8090		
DFTG. CHK.		TO-263, MOLDED, 3 LEAD, SURFACE MOUNT		
ENGR. CHK.				
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
	N/A	C	MKT-TS3B	E
INCH [MM]		DO NOT SCALE DRAWING		SHEET 1 OF 1